

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MICROCONTROLLERS/24/14728	
1.3 Title of PCN	ASE KaoHsiung (Taiwan) LQFP14x14 and LQFP20x20 package copper palladium bonding wire introduction on STM32H5x and STM32U5x listed products.	
1.4 Product Category	STM32H56x, STM32H57x STM32U53x, STM32U54x STM32U57x, STM32U58x STM32U59x, STM32U5Ax STM32U5Fx, STM32U5Gx	
1.5 Issue date	2024-07-19	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Direct Material: Bond Wire - Metallurgy (metallic composition/ raw material)	ASE Kaohsiung (TAIWAN)

4. Description of change

	Old	New
4.1 Description	Current Wire bonding material: - ASE KaoHsiung (Taiwan) gold wire	New Wire bonding material : - ASE KaoHsiung (Taiwan) copper palladium wire
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact on form, Fit, Function	

5. Reason / motivation for change

5.1 Motivation	To improve service
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	traceability ensured by ST Internal tools
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7. Timing / schedule

7.1 Date of qualification results	2024-07-12
7.2 Intended start of delivery	2024-10-01
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	14728 MDG-GPM-RER2304-PCN13841 14224 14728 V3-ASE LQFP7 to 20 CuPd wire-RER report.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2024-07-19

9. Attachments (additional documentations)
14728 Public product.pdf 14728 MDG-GPM-RER2304-PCN13841 14224 14728 V3-ASE LQFP7 to 20 CuPd wire-RER report.pdf 14728 PCN14728 Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H563VIT6	
	STM32H563ZIT6	
	STM32H573VIT3Q	
	STM32H573VIT6	
	STM32H573ZIT3Q	
	STM32H573ZIT6	
	STM32U545VET6Q	
	STM32U575VIT6	
	STM32U575VIT6Q	
	STM32U575ZIT6	
	STM32U575ZIT6Q	
	STM32U585VIT6	
	STM32U585VIT6Q	
	STM32U595VJT6	
	STM32U595ZJT6Q	
	STM32U599VJT6	
	STM32U5A5VJT6Q	
	STM32U5A9ZJT6Q	
	STM32U5G7VJT6Q	
	STM32U5G9VJT6Q	
	STM32U5G9ZJT6Q	



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : ASE KaoHsiung (Taiwan) LQFP14x14 and LQFP20x20 package copper palladium bonding wire introduction on STM32H5x and STM32U5x listed products.

PCN Reference : MICROCONTROLLERS/24/14728

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32U595VIT6QTR	STM32U535VET3QTR	STM32U575ZGT3QTR
STM32U585VIT6QTR	STM32U585ZIT3QTR	STM32U575ZIT3QTR
STM32H563ZIT3QTR	STM32U575VIT6QTR	STM32U599VJT6
STM32U585VIT6TR	STM32U575ZIT6Q	STM32U575ZGT6Q
STM32U595ZJT6Q	STM32U595ZIT6Q	STM32U575VIT6TR
STM32U585VIT3	STM32U585ZIT3Q	STM32H562VGT6
STM32U585VIT6Q	STM32U535VET6	STM32U575ZGT3
STM32H573ZIT6	STM32U575VIT6	STM32U575VGT3
STM32U599VJT6Q	STM32U5F7VJT6	STM32U535VET3Q
STM32U585ZIT6Q	STM32H563ZGT6	STM32U599VIT6Q
STM32U545VET6	STM32U575VGT6Q	STM32U5A5ZJT6TR
STM32U595VJT6Q	STM32U575VGT6TR	STM32H563ZGT6TR
STM32U595VIT6Q	STM32U585VIT3TR	STM32U535VET6Q
STM32U575VGT3TR	STM32U575VIT6Q	STM32U595VIT6
STM32U545VET6Q	STM32U5A9ZJT6Q	STM32U575ZGT3Q
STM32U599ZIT6Q	STM32U5A5ZJT6	STM32U575ZIT6TR
STM32U5A9VJT6Q	STM32U595ZIT6	STM32U575ZIT3Q
STM32U585VIT3Q	STM32U5A5VJT6	STM32U595ZJT6
STM32U5G9VJT6Q	STM32H573VIT3Q	STM32H562VIT6
STM32H563VIT6	STM32U595VJT6	STM32U535VCT6
STM32U575VGT6	STM32U575ZIT6	STM32U585VIT6
STM32U585ZIT6	STM32U599ZJT6Q	STM32U575ZGT6
STM32U595VJT3Q	STM32U535VCT6Q	STM32U5G9ZJT6Q
STM32U5G7VJT6	STM32U5F9ZJT6Q	STM32H563VGT6TR
STM32H562ZGT6	STM32U5A5VJT6Q	STM32U5F9VJT6Q
STM32U5G7VJT6Q	STM32H562ZGT6TR	STM32U5A5ZJT6Q
STM32H563ZIT6	STM32H563VIT3Q	STM32H562ZIT6
STM32H563VIT6TR	STM32H562VGT6TR	STM32H573ZIT3Q
STM32U5F7VJT6Q	STM32H573VIT6TR	STM32H563VGT6
STM32H563ZIT3Q	STM32H573VIT6	

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